

LASER DEVICE

Patent Number: JP2090585
Publication date: 1990-03-30
Inventor(s): OGAWA TAKESHI
Applicant(s): NEC CORP
Requested Patent: ☐ JP2090585
Application Number: JP19880242795 19880927
Priority Number(s):
IPC Classification: H01S3/18; H01L31/12
EC Classification:
Equivalents:

Abstract

PURPOSE:To facilitate the mounting and bonding of a laser chip so as to improve a laser device in productivity and manufacturing yield by a method wherein the laser chip mounted on the upside of a mount and a photodetecting element are provided, and the photodetecting element is installed making its light detecting face tilted by a specified angle with light emitted from the laser chip.

CONSTITUTION:A laser chip 1 is mounted on the upside of a mount 5 formed on a stem 4 of a package. A monitoring photodetective element 3 provided with a reflective film 6 whose reflectivity is 80-95% formed on its surface is installed making an angle of 45 degrees with light rays outputted from the laser chip 1. Light rays outputted from the laser chip 1 is reflected from the surface of the monitoring photodetecting element 3 and 80-95% of it is taken outside as a primary beam 2 through a window. The rest, 5-10% of the light, is made to be incident on a monitoring photodetective element 3 as monitored light rays.

Data supplied from the esp@cenet database - I2



(19)

(11) Publication number:

0

Generated Document.

PATENT ABSTRACTS OF JAPAN(21) Application number: **63242795**(51) Intl. Cl.: **H01S 3/18 H01L 31/12**(22) Application date: **27.09.88**

<p>(30) Priority:</p> <p>(43) Date of application publication: 30.03.90</p> <p>(84) Designated contracting states:</p>	<p>(71) Applicant: NEC CORP</p> <p>(72) Inventor: OGAWA TAKESHI</p> <p>(74) Representative:</p>
---	---

(54) LASER DEVICE

(57) Abstract:

PURPOSE: To facilitate the mounting and bonding of a laser chip so as to improve a laser device in productivity and manufacturing yield by a method wherein the laser chip mounted on the upside of a mount and a photodetecting element are provided, and the photodetecting element is installed making its light detecting face tilted by a specified angle with light emitted from the laser chip.

CONSTITUTION: A laser chip 1 is mounted on the upside of a mount 5 formed on a stem 4 of a package. A monitoring photodetective element 3 provided with a reflective film 6 whose reflectivity is 80-95% formed on its surface is installed making an angle of 45 degrees with light rays outputted from the laser chip 1. Light rays outputted from the laser chip 1 is reflected from the surface of the monitoring photodetecting element 3 and 80-95% of it is taken outside as a

primary beam 2 through a window. The rest, 5-10% of the light, is made to be incident on a monitoring photodetective element 3 as monitored light rays.

COPYRIGHT: (C)1990,JPO&Japio

